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### **Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems**

**Embedded - System On Chip (SoC)** refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

### **What are Embedded - System On Chip (SoC)?**

**System On Chip (SoC)** integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

#### **Details**

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Quad ARM® Cortex®-A53 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, WDT
Connectivity	EBI/EMI, Ethernet, I <sup>2</sup> C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 2800K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	2912-BBGA, FCBGA
Supplier Device Package	2912-FBGA, FC (55x55)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/1sx280lh2f55i2vg">https://www.e-xfl.com/product-detail/intel/1sx280lh2f55i2vg</a>



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## 1. Intel® Stratix® 10 GX/SX Device Overview

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Intel's 14-nm Intel® Stratix® 10 GX FPGAs and SX SoCs deliver 2X the core performance and up to 70% lower power over previous generation high-performance FPGAs.

Featuring several groundbreaking innovations, including the all new HyperFlex™ core architecture, this device family enables you to meet the demand for ever-increasing bandwidth and processing performance in your most advanced applications, while meeting your power budget.

With an embedded hard processor system (HPS) based on a quad-core 64-bit ARM® Cortex®-A53, the Intel Stratix 10 SoC devices deliver power efficient, application-class processing and allow designers to extend hardware virtualization into the FPGA fabric. Intel Stratix 10 SoC devices demonstrate Intel's commitment to high-performance SoCs and extend Intel's leadership in programmable devices featuring an ARM-based processor system.

Important innovations in Intel Stratix 10 FPGAs and SoCs include:

- All new HyperFlex core architecture delivering 2X the core performance compared to previous generation high-performance FPGAs
- Industry leading Intel 14-nm Tri-Gate (FinFET) technology
- Heterogeneous 3D System-in-Package (SiP) technology
- Monolithic core fabric with up to 5.5 million logic elements (LEs)
- Up to 96 full duplex transceiver channels on heterogeneous 3D SiP transceiver tiles
- Transceiver data rates up to 28.3 Gbps chip-to-chip/module and backplane performance
- M20K (20 kbit) internal SRAM memory blocks
- Fractional synthesis and ultra-low jitter LC tank based transmit phase locked loops (PLLs)
- Hard PCI Express® Gen3 x16 intellectual property (IP) blocks
- Hard 10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC) in every transceiver channel
- Hard memory controllers and PHY supporting DDR4 rates up to 2666 Mbps per pin
- Hard fixed-point and IEEE 754 compliant hard floating-point variable precision digital signal processing (DSP) blocks with up to 10 TFLOPS compute performance with a power efficiency of 80 GFLOPS per Watt
- Quad-core 64-bit ARM Cortex-A53 embedded processor running up to 1.5 GHz in SoC family variants
- Programmable clock tree synthesis for flexible, low power, low skew clock trees

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ISO  
9001:2015  
Registered



- Dedicated secure device manager (SDM) for:
  - Enhanced device configuration and security
  - AES-256, SHA-256/384 and ECDSA-256/384 encrypt/decrypt accelerators and authentication
  - Multi-factor authentication
  - Physically Unclonable Function (PUF) service and software programmable device configuration capability
- Comprehensive set of advanced power saving features delivering up to 70% lower power compared to previous generation high-performance FPGAs
- Non-destructive register state readback and writeback, to support ASIC prototyping and other applications

With these capabilities, Intel Stratix 10 FPGAs and SoCs are ideally suited for the most demanding applications in diverse markets such as:

- **Compute and Storage**—for custom servers, cloud computing and data center acceleration
- **Networking**—for Terabit, 400G and multi-100G bridging, aggregation, packet processing and traffic management
- **Optical Transport Networks**—for OTU4, 2xOTU4, 4xOTU4
- **Broadcast**—for high-end studio distribution, headend encoding/decoding, edge quadrature amplitude modulation (QAM)
- **Military**—for radar, electronic warfare, and secure communications
- **Medical**—for diagnostic scanners and diagnostic imaging
- **Test and Measurement**—for protocol and application testers
- **Wireless**—for next-generation 5G networks
- **ASIC Prototyping**—for designs that require the largest monolithic FPGA fabric with the highest I/O count

## 1.1. Intel Stratix 10 Family Variants

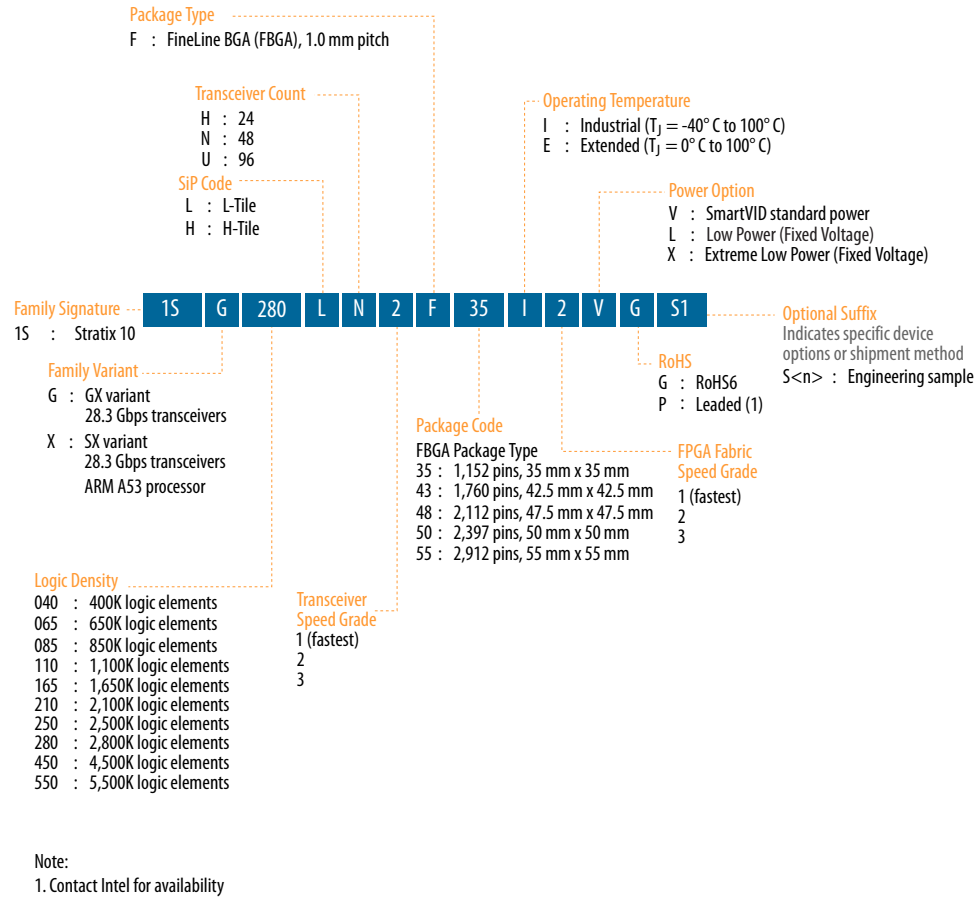
Intel Stratix 10 devices are available in FPGA (GX) and SoC (SX) variants.

- **Intel Stratix 10 GX** devices deliver up to 1 GHz core fabric performance and contain up to 5.5 million LEs in a monolithic fabric. They also feature up to 96 general purpose transceivers on separate transceiver tiles, and 2666 Mbps DDR4 external memory interface performance. The transceivers are capable of up to 28.3 Gbps short reach and across the backplane. These devices are optimized for FPGA applications that require the highest transceiver bandwidth and core fabric performance, with the power efficiency of Intel's industry-leading 14-nm Tri-Gate process technology.
- **Intel Stratix 10 SX** devices have a feature set that is identical to Intel Stratix 10 GX devices, with the addition of an embedded quad-core 64-bit ARM Cortex A53 hard processor system.



### 1.1.1. Available Options

**Figure 1. Sample Ordering Code and Available Options for Intel Stratix 10 Devices**



## 1.2. Innovations in Intel Stratix 10 FPGAs and SoCs

Intel Stratix 10 FPGAs and SoCs deliver many significant improvements over the previous generation high-performance Stratix V FPGAs.

**Table 1. Key Features of Intel Stratix 10 Devices Compared to Stratix V Devices**

Feature	Stratix V FPGAs	Intel Stratix 10 FPGAs and SoCs
<b>Process technology</b>	28-nm TSMC (planar transistor)	14 nm Intel Tri-Gate (FinFET)
<b>Hard processor core</b>	None	Quad-core 64-bit ARM Cortex-A53 (SoC only)
<b>Core architecture</b>	Conventional core architecture with conventional interconnect	HyperFlex core architecture with Hyper-Registers in the interconnect
<b>Core performance</b>	500 MHz	1 GHz
<b>Power dissipation</b>	1x	As low as 0.3x
<i>continued...</i>		



Feature	Description
Power management	<ul style="list-style-type: none"> <li>SmartVID controlled core voltage, standard power devices</li> <li>0.85-V fixed core voltage, low static power devices available</li> <li>Intel Quartus® Prime Pro Edition integrated power analysis</li> </ul>
High performance monolithic core fabric	<ul style="list-style-type: none"> <li>HyperFlex core architecture with Hyper-Registers throughout the interconnect routing and at the inputs of all functional blocks</li> <li>Monolithic fabric minimizes compile times and increases logic utilization</li> <li>Enhanced adaptive logic module (ALM)</li> <li>Improved multi-track routing architecture reduces congestion and improves compile times</li> <li>Hierarchical core clocking architecture with programmable clock tree synthesis</li> <li>Fine-grained partial reconfiguration</li> </ul>
Internal memory blocks	<ul style="list-style-type: none"> <li>M20K—20-Kbit with hard ECC support</li> <li>MLAB—640-bit distributed LUTRAM</li> </ul>
Variable precision DSP blocks	<ul style="list-style-type: none"> <li>IEEE 754-compliant hard single-precision floating point capability</li> <li>Supports signal processing with precision ranging from 18x19 up to 54x54</li> <li>Native 27x27 and 18x19 multiply modes</li> <li>64-bit accumulator and cascade for systolic FIRs</li> <li>Internal coefficient memory banks</li> <li>Pre-adder/subtractor improves efficiency</li> <li>Additional pipeline register increases performance and reduces power</li> </ul>
Phase locked loops (PLL)	<ul style="list-style-type: none"> <li>Fractional synthesis PLLs (fPLL) support both fractional and integer modes</li> <li>Fractional mode with third-order delta-sigma modulation</li> <li>Precision frequency synthesis</li> <li>Integer PLLs adjacent to general purpose I/Os, support external memory, and LVDS interfaces, clock delay compensation, zero delay buffering</li> </ul>
Core clock networks	<ul style="list-style-type: none"> <li>1 GHz fabric clocking</li> <li>667 MHz external memory interface clocking, supports 2666 Mbps DDR4 interface</li> <li>800 MHz LVDS interface clocking, supports 1600 Mbps LVDS interface</li> <li>Programmable clock tree synthesis, backwards compatible with global, regional and peripheral clock networks</li> <li>Clocks only synthesized where needed, to minimize dynamic power</li> </ul>
continued...	



Feature	Description
Configuration	<ul style="list-style-type: none"><li>• Dedicated Secure Device Manager</li><li>• Software programmable device configuration</li><li>• Serial and parallel flash interface</li><li>• Configuration via protocol (CvP) using PCI Express Gen1/Gen2/Gen3</li><li>• Fine-grained partial reconfiguration of core fabric</li><li>• Dynamic reconfiguration of transceivers and PLLs</li><li>• Comprehensive set of security features including AES-256, SHA-256/384, and ECDSA-256/384 accelerators, and multi-factor authentication</li><li>• Physically Unclonable Function (PUF) service</li></ul>
Packaging	<ul style="list-style-type: none"><li>• Intel Embedded Multi-die Interconnect Bridge (EMIB) packaging technology</li><li>• Multiple devices with identical package footprints allows seamless migration across different device densities</li><li>• 1.0 mm ball-pitch FBGA packaging</li><li>• Lead and lead-free package options</li></ul>
Software and tools	<ul style="list-style-type: none"><li>• Intel Quartus Prime Pro Edition design suite with new compiler and Hyper-Aware design flow</li><li>• Fast Forward compiler to allow HyperFlex architecture performance exploration</li><li>• Transceiver toolkit</li><li>• Platform designer integration tool</li><li>• DSP Builder advanced blockset</li><li>• OpenCL™ support</li><li>• SoC Embedded Design Suite (EDS)</li></ul>

Table 3. Intel Stratix 10 SoC Specific Device Features

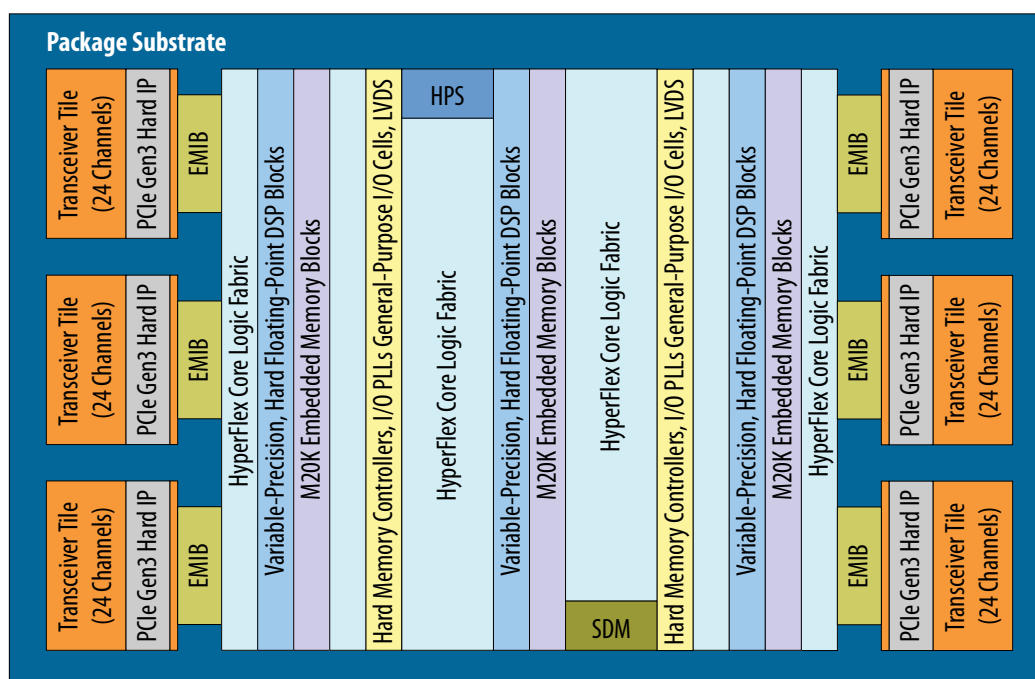
SoC Subsystem	Feature	Description
<b>Hard Processor System</b>	Multi-processor unit (MPU) core	<ul style="list-style-type: none"><li>• Quad-core ARM Cortex-A53 MPCore processor with ARM CoreSight debug and trace technology</li><li>• Scalar floating-point unit supporting single and double precision</li><li>• ARM NEON media processing engine for each processor</li></ul>
	System Controllers	<ul style="list-style-type: none"><li>• System Memory Management Unit (SMMU)</li><li>• Cache Coherency Unit (CCU)</li></ul>
	Layer 1 Cache	<ul style="list-style-type: none"><li>• 32 KB L1 instruction cache with parity</li><li>• 32 KB L1 data cache with ECC</li></ul>
	Layer 2 Cache	<ul style="list-style-type: none"><li>• 1 MB Shared L2 Cache with ECC</li></ul>
	On-Chip Memory	<ul style="list-style-type: none"><li>• 256 KB On-Chip RAM</li></ul>
	Direct memory access (DMA) controller	<ul style="list-style-type: none"><li>• 8-Channel DMA</li></ul>
	Ethernet media access controller (EMAC)	<ul style="list-style-type: none"><li>• Three 10/100/1000 EMAC with integrated DMA</li></ul>
	USB On-The-Go controller (OTG)	<ul style="list-style-type: none"><li>• 2 USB OTG with integrated DMA</li></ul>
	UART controller	<ul style="list-style-type: none"><li>• 2 UART 16550 compatible</li></ul>
	Serial Peripheral Interface (SPI) controller	<ul style="list-style-type: none"><li>• 4 SPI</li></ul>
	I <sup>2</sup> C controller	<ul style="list-style-type: none"><li>• 5 I<sup>2</sup>C controllers</li></ul>
	SD/SDIO/MMC controller	<ul style="list-style-type: none"><li>• 1 eMMC version 4.5 with DMA and CE-ATA support</li><li>• SD, including eSD, version 3.0</li><li>• SDIO, including eSDIO, version 3.0</li><li>• CE-ATA - version 1.1</li></ul>
continued...		



SoC Subsystem	Feature	Description
	NAND flash controller	<ul style="list-style-type: none"> <li>1 ONFI 1.0, 8- and 16-bit support</li> </ul>
	General-purpose I/O (GPIO)	<ul style="list-style-type: none"> <li>Maximum of 48 software programmable GPIO</li> </ul>
	Timers	<ul style="list-style-type: none"> <li>4 general-purpose timers</li> <li>4 watchdog timers</li> </ul>
<b>Secure Device Manager</b>	Security	<ul style="list-style-type: none"> <li>Secure boot</li> <li>Advanced Encryption Standard (AES) and authentication (SHA/ECDSA)</li> </ul>
<b>External Memory Interface</b>	External Memory Interface	<ul style="list-style-type: none"> <li>Hard Memory Controller with DDR4 and DDR3, and LPDDR3</li> </ul>

## 1.4. Intel Stratix 10 Block Diagram

Figure 2. Intel Stratix 10 FPGA and SoC Architecture Block Diagram



HPS: Quad ARM Cortex-A53 Hard Processor System

SDM: Secure Device Manager

EMIB: Embedded Multi-Die Interconnect Bridge

## 1.5. Intel Stratix 10 FPGA and SoC Family Plan

(1) The number of 27x27 multipliers is one-half the number of 18x19 multipliers.





**Table 4. Intel Stratix 10 GX/SX FPGA and SoC Family Plan—FPGA Core (part 1)**

Intel Stratix 10 GX/SX Device Name	Logic Elements (KLE)	M20K Blocks	M20K Mbits	MLAB Counts	MLAB Mbits	18x19 Multipliers <sup>(1)</sup>
GX 400/ SX 400	378	1,537	30	3,204	2	1,296
GX 650/ SX 650	612	2,489	49	5,184	3	2,304
GX 850/ SX 850	841	3,477	68	7,124	4	4,032
GX 1100/ SX 1100	1,092	4,401	86	9,540	6	5,040
GX 1650/ SX 1650	1,624	5,851	114	13,764	8	6,290
GX 2100/ SX 2100	2,005	6,501	127	17,316	11	7,488
GX 2500/ SX 2500	2,422	9,963	195	20,529	13	10,022
GX 2800/ SX 2800	2,753	11,721	229	23,796	15	11,520
GX 4500/ SX 4500	4,463	7,033	137	37,821	23	3,960
GX 5500/ SX 5500	5,510	7,033	137	47,700	29	3,960

**Table 5. Intel Stratix 10 GX/SX FPGA and SoC Family Plan—Interconnects, PLLs and Hard IP (part 2)**

Intel Stratix 10 GX/SX Device Name	Interconnects		PLLs		Hard IP
	Maximum GPIOs	Maximum XCVR	fPLLs	I/O PLLs	PCIe Hard IP Blocks
GX 400/ SX 400	392	24	8	8	1
GX 650/ SX 650	400	48	16	8	2
GX 850/ SX 850	736	48	16	15	2
GX 1100/ SX 1100	736	48	16	15	2
GX 1650/ SX 1650	704	96	32	14	4
GX 2100/ SX 2100	704	96	32	14	4
GX 2500/ SX 2500	1160	96	32	24	4
continued...					



Intel Stratix 10 GX/SX Device Name	Interconnects		PLLs		Hard IP
	Maximum GPIOs	Maximum XCVR	fPLLs	I/O PLLs	PCIe Hard IP Blocks
GX 2800/ SX 2800	1160	96	32	24	4
GX 4500/ SX 4500	1640	24	8	34	1
GX 5500/ SX 5500	1640	24	8	34	1

**Table 6. Intel Stratix 10 GX/SX FPGA and SoC Family Package Plan, part 1**Cell legend: General Purpose I/Os, High-Voltage I/Os, LVDS Pairs, Transceivers <sup>(2)</sup> <sup>(3)</sup> <sup>(4)</sup> <sup>(5)</sup> <sup>(6)</sup> <sup>(7)</sup>

Intel Stratix 10 GX/SX Device Name	F1152 HF35 (35x35 mm <sup>2</sup> )	F1760 NF43 (42.5x42.5 mm <sup>2</sup> )	F1760 NF43 (42.5x42.5 mm <sup>2</sup> )
GX 400/ SX 400	392, 8, 192, 24		
GX 650/ SX 650	392, 8, 192, 24	400, 16, 192, 48	
GX 850/ SX 850			688, 16, 336, 48
GX 1100/ SX 1100			688, 16, 336, 48
GX 1650/ SX 1650			688, 16, 336, 48
GX 2100/ SX 2100			688, 16, 336, 48
GX 2500/ SX 2500			688, 16, 336, 48
GX 2800/ SX 2800			688, 16, 336, 48
<b>continued...</b>			

<sup>(2)</sup> All packages are ball grid arrays with 1.0 mm pitch.<sup>(3)</sup> High-Voltage I/O pins are used for 3 V and 2.5 V interfacing.<sup>(4)</sup> Each LVDS pair can be configured as either a differential input or a differential output.<sup>(5)</sup> High-Voltage I/O pins and LVDS pairs are included in the General Purpose I/O count. Transceivers are counted separately.<sup>(6)</sup> Each package column offers pin migration (common circuit board footprint) for all devices in the column.<sup>(7)</sup> Intel Stratix 10 GX devices are pin migratable with Intel Stratix 10 SX devices in the same package.



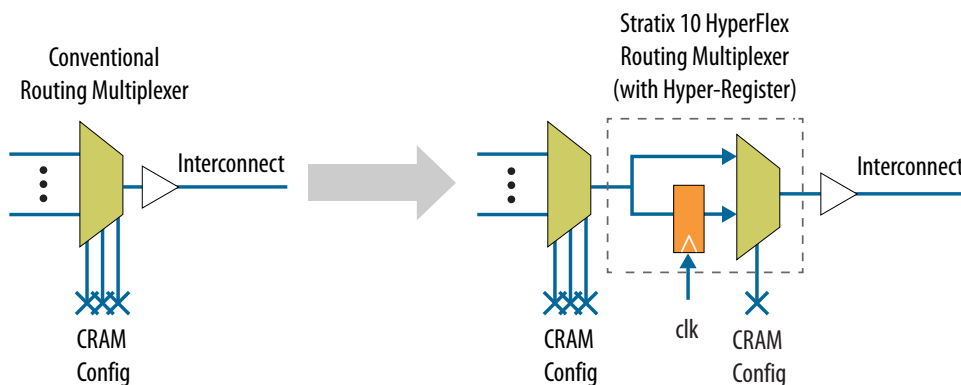
## 1.6. HyperFlex Core Architecture

Intel Stratix 10 FPGAs and SoCs are based on a monolithic core fabric featuring the new HyperFlex core architecture. The HyperFlex core architecture delivers 2X the clock frequency performance and up to 70% lower power compared to previous generation high-end FPGAs. Along with this performance breakthrough, the HyperFlex core architecture delivers a number of advantages including:

- **Higher Throughput**—Leverages 2X core clock frequency performance to obtain throughput breakthroughs
- **Improved Power Efficiency**—Uses reduced IP size, enabled by HyperFlex, to consolidate designs which previously spanned multiple devices into a single device, thereby reducing power by up to 70% versus previous generation devices
- **Greater Design Functionality**—Uses faster clock frequency to reduce bus widths and reduce IP size, freeing up additional FPGA resources to add greater functionality
- **Increased Designer Productivity**—Boosts performance with less routing congestion and fewer design iterations using Hyper-Aware design tools, obtaining greater timing margin for more rapid timing closure

In addition to the traditional user registers found in the Adaptive Logic Modules (ALM), the HyperFlex core architecture introduces additional bypassable registers everywhere throughout the fabric of the FPGA. These additional registers, called Hyper-Registers are available on every interconnect routing segment and at the inputs of all functional blocks.

**Figure 3. Bypassable Hyper-Register**



The Hyper-Registers enable the following key design techniques to achieve the 2X core performance increases:

- Fine grain Hyper-Retiming to eliminate critical paths
- Zero latency Hyper-Pipelining to eliminate routing delays
- Flexible Hyper-Optimization for best-in-class performance

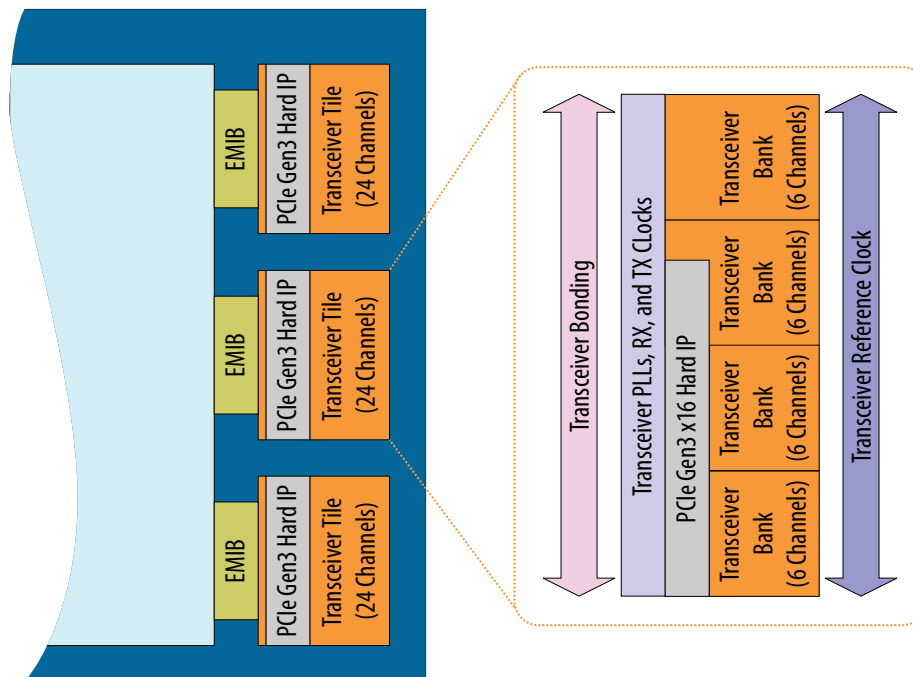
By implementing these techniques in your design, the Hyper-Aware design tools automatically make use of the Hyper-Registers to achieve maximum core clock frequency.



Each transceiver tile contains:

- 24 full-duplex transceiver channels (PMA and PCS)
- Reference clock distribution network
- Transmit PLLs
- High-speed clocking and bonding networks
- One instance of PCI Express hard IP

**Figure 6. Heterogeneous 3D SiP Transceiver Tile Architecture**

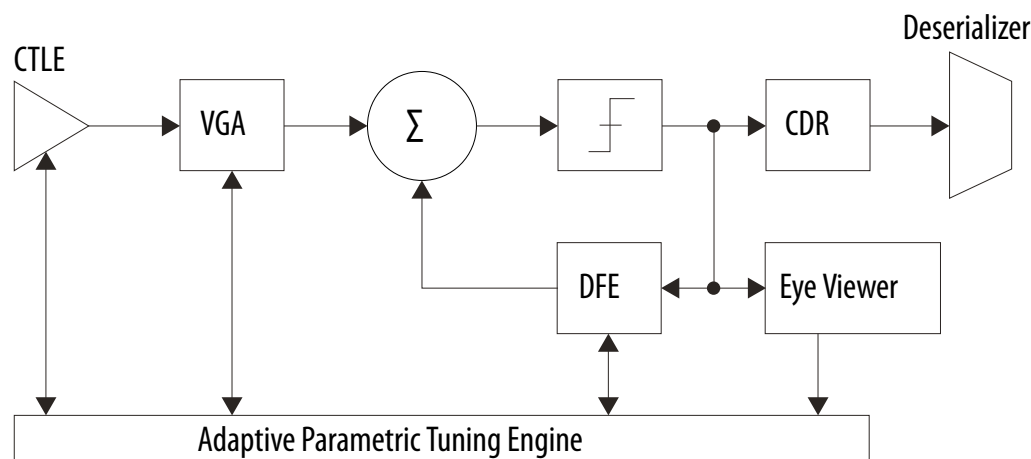


## 1.8. Intel Stratix 10 Transceivers

Intel Stratix 10 devices offer up to 96 total full-duplex transceiver channels. These channels provide continuous data rates from 1 Gbps to 28.3 Gbps for chip-to-chip, chip-to-module, and backplane applications. In each device, two thirds of the transceivers can be configured up to the maximum data rate of 28.3 Gbps to drive 100G interfaces and C form-factor pluggable CFP2/CFP4 optical modules. For longer-reach backplane driving applications, advanced adaptive equalization circuits are used to equalize over 30 dB of system loss.

All transceiver channels feature a dedicated Physical Medium Attachment (PMA) and a hardened Physical Coding Sublayer (PCS).

- The PMA provides primary interfacing capabilities to physical channels.
- The PCS typically handles encoding/decoding, word alignment, and other pre-processing functions before transferring data to the FPGA core fabric.

**Figure 7. Intel Stratix 10 Receiver Block Features**

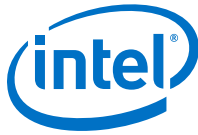
All link equalization parameters feature automatic adaptation using the new Advanced Digital Adaptive Parametric Tuning (ADAPT) circuit. This circuit is used to dynamically set DFE tap weights, adjust CTLE parameters, and optimize VGA gain and threshold voltage. Finally, optimal and consistent signal integrity is ensured by using the new hardened Precision Signal Integrity Calibration Engine (PreSICE) to automatically calibrate all transceiver circuit blocks on power-up. This gives the most link margin and ensures robust, reliable, and error-free operation.

**Table 8. Transceiver PMA Features**

Feature	Capability
Chip-to-Chip Data Rates	1 Gbps <sup>(8)</sup> to 28.3 Gbps (Intel Stratix 10 GX/SX devices)
Backplane Support	Drive backplanes at data rates up to 28.3 Gbps, including 10GBASE-KR compliance
Optical Module Support	SFP+/SFP, XFP, CXP, QSFP/QSFP28, QSFPDD, CFP/CFP2/CFP4
Cable Driving Support	SFP+ Direct Attach, PCI Express over cable, eSATA
Transmit Pre-Emphasis	5-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss
Continuous Time Linear Equalizer (CTLE)	Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss
Decision Feedback Equalizer (DFE)	15 fixed tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments
Advanced Digital Adaptive Parametric Tuning (ADAPT)	Fully digital adaptation engine to automatically adjust all link equalization parameters—including CTLE, DFE, and VGA blocks—that provide optimal link margin without intervention from user logic
Precision Signal Integrity Calibration Engine (PreSICE)	Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance
ATX Transmit PLLs	Low jitter ATX (inductor-capacitor) transmit PLLs with continuous tuning range to cover a wide range of standard and proprietary protocols, with optional fractional frequency synthesis capability
Fractional PLLs	On-chip fractional frequency synthesizers to replace on-board crystal oscillators and reduce system cost

*continued...*

<sup>(8)</sup> Stratix 10 transceivers can support data rates below 1 Gbps with over sampling.



Feature	Capability
Digitally Assisted Analog CDR	Superior jitter tolerance with fast lock time
On-Die Instrumentation—Eye Viewer and Jitter Margin Tool	Simplify board bring-up, debug, and diagnostics with non-intrusive, high-resolution eye monitoring (Eye Viewer). Also inject jitter from transmitter to test link margin in system.
Dynamic Reconfiguration	Allows for independent control of each transceiver channel Avalon memory-mapped interface for the most transceiver flexibility.
Multiple PCS-PMA and PCS-Core to FPGA fabric interface widths	8-, 10-, 16-, 20-, 32-, 40-, or 64-bit interface widths for flexibility of deserialization width, encoding, and reduced latency

## 1.8.2. PCS Features

Intel Stratix 10 PMA channels interface with core logic through configurable and bypassable PCS interface layers.

The PCS contains multiple gearbox implementations to decouple the PMA and PCS interface widths. This feature provides the flexibility to implement a wide range of applications with 8, 10, 16, 20, 32, 40, or 64-bit interface width between each transceiver and the core logic.

The PCS also contains hard IP to support a variety of standard and proprietary protocols across a wide range of data rates and encoding schemes. The Standard PCS mode provides support for 8B/10B encoded applications up to 12.5 Gbps. The Enhanced PCS mode supports 64B/66B and 64B/67B encoded applications up to 17.4 Gbps. The enhanced PCS mode also includes an integrated 10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC) circuit. For highly customized implementations, a PCS Direct mode provides an interface up to 64 bits wide to allow for custom encoding and support for data rates up to 28.3 Gbps.

For more information about the PCS-Core interface or the double rate transfer mode, refer to the *Intel Stratix 10 L- and H-Tile Transceiver PHY User Guide*, and the *Intel Stratix 10 E-Tile Transceiver PHY User Guide*.

**Table 9. Transceiver PCS Features**

PCS Protocol Support	Data Rate (Gbps)	Transmitter Data Path	Receiver Data Path
Standard PCS	1 to 12.5	Phase compensation FIFO, byte serializer, 8B/10B encoder, bit-slipper, channel bonding	Rate match FIFO, word-aligner, 8B/10B decoder, byte deserializer, byte ordering
PCI Express Gen1/Gen2 x1, x2, x4, x8, x16	2.5 and 5.0	Same as Standard PCS plus PIPE 2.0 interface to core	Same as Standard PCS plus PIPE 2.0 interface to core
PCI Express Gen3 x1, x2, x4, x8, x16	8.0	Phase compensation FIFO, byte serializer, encoder, scrambler, bit-slipper, gear box, channel bonding, and PIPE 3.0 interface to core, auto speed negotiation	Rate match FIFO (0-600 ppm mode), word-aligner, decoder, descrambler, phase compensation FIFO, block sync, byte deserializer, byte ordering, PIPE 3.0 interface to core, auto speed negotiation
CPRI	0.6144 to 9.8	Same as Standard PCS plus deterministic latency serialization	Same as Standard PCS plus deterministic latency deserialization
continued...			



Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller capable of supporting many different memory types, each with different performance capabilities. The hard memory controller is also capable of being bypassed and replaced by a soft controller implemented in the user logic. The I/Os each have a hardened double data rate (DDR) read/write path (PHY) capable of performing key memory interface functionality such as:

- Read/write leveling
- FIFO buffering to lower latency and improve margin
- Timing calibration
- On-chip termination

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios® II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Stratix 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Stratix 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

**Table 10. External Memory Interface Performance**

The listed speeds are for the 1-rank case.

Interface	Controller Type	Performance
DDR4	Hard	2666 Mbps
DDR3	Hard	2133 Mbps
QDRII+	Soft	1,100 Mtps
QDRII+ Xtreme	Soft	1,266 Mtps
QDRIV	Soft	2,133 Mtps
RLDRAM III	Soft	2400 Mbps
RLDRAM II	Soft	533 Mbps

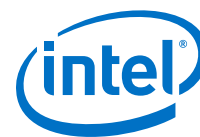
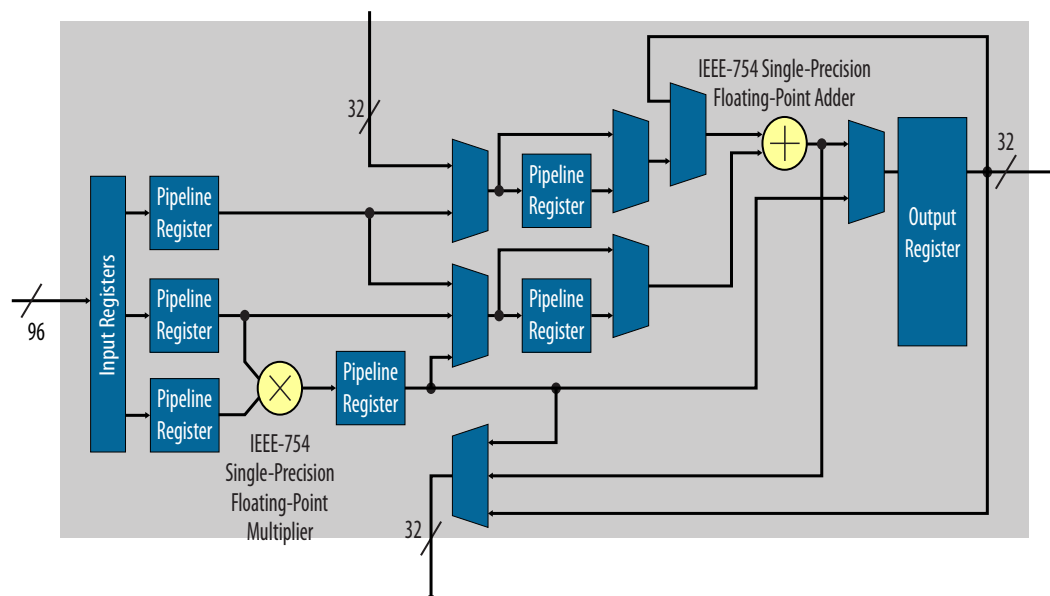
In addition to parallel memory interfaces, Intel Stratix 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Stratix 10 high-speed serial transceivers, which connect up to four HMC links, with each link running at data rates of 15 Gbps (HMC short reach specification).

Intel Stratix 10 devices also feature general purpose I/Os capable of supporting a wide range of single-ended and differential I/O interfaces. LVDS rates up to 1.6 Gbps are supported, with each pair of pins having both a differential driver and a differential input buffer. This enables configurable direction for each LVDS pair.

### 1.13. Adaptive Logic Module (ALM)

Intel Stratix 10 devices use a similar adaptive logic module (ALM) as the previous generation Arria 10 and Stratix V FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the devices.

The ALM block diagram shown in the following figure has eight inputs with a fracturable look-up table (LUT), two dedicated embedded adders, and four dedicated registers.

**Figure 12. DSP Block: Single Precision Floating Point Mode**

Each DSP block can be independently configured at compile time as either dual 18x19 or a single 27x27 multiply accumulate. With a dedicated 64-bit cascade bus, multiple variable precision DSP blocks can be cascaded to implement even higher precision DSP functions efficiently.

In floating point mode, each DSP block provides one single precision floating point multiplier and adder. Floating point additions, multiplications, mult-adds and mult-accumulates are supported.

The following table shows how different precisions are accommodated within a DSP block, or by utilizing multiple blocks.

**Table 12. Variable Precision DSP Block Configurations**

Multiplier Size	DSP Block Resources	Expected Usage
18x19 bits	1/2 of Variable Precision DSP Block	Medium precision fixed point
27x27 bits	1 Variable Precision DSP Block	High precision fixed point
19x36 bits	1 Variable Precision DSP Block with external adder	Fixed point FFTs
36x36 bits	2 Variable Precision DSP Blocks with external adder	Very high precision fixed point
54x54 bits	4 Variable Precision DSP Blocks with external adder	Double Precision floating point
Single Precision floating point	1 Single Precision floating point adder, 1 Single Precision floating point multiplier	Floating point





Complex multiplication is very common in DSP algorithms. One of the most popular applications of complex multipliers is the FFT algorithm. This algorithm has the characteristic of increasing precision requirements on only one side of the multiplier. The Variable Precision DSP block supports the FFT algorithm with proportional increase in DSP resources as the precision grows.

**Table 13. Complex Multiplication With Variable Precision DSP Block**

Complex Multiplier Size	DSP Block Resources	FFT Usage
18x19 bits	2 Variable Precision DSP Blocks	Resource optimized FFT
27x27 bits	4 Variable Precision DSP Blocks	Highest precision FFT

For FFT applications with high dynamic range requirements, the Intel FFT IP Core offers an option of single precision floating point implementation with resource usage and performance similar to high precision fixed point implementations.

Other features of the DSP block include:

- Hard 18-bit and 25-bit pre-adders
- Hard floating point multipliers and adders
- 64-bit dual accumulator (for separate I, Q product accumulations)
- Cascaded output adder chains for 18- and 27-bit FIR filters
- Embedded coefficient registers for 18- and 27-bit coefficients
- Fully independent multiplier outputs
- Inferability using HDL templates supplied by the Intel Quartus Prime software for most modes

The Variable Precision DSP block is ideal to support the growing trend towards higher bit precision in high performance DSP applications. At the same time, it can efficiently support the many existing 18-bit DSP applications, such as high definition video processing and remote radio heads. With the Variable Precision DSP block architecture and hard floating point multipliers and adders, Intel Stratix 10 devices can efficiently support many different precision levels up to and including floating point implementations. This flexibility can result in increased system performance, reduced power consumption, and reduce architecture constraints on system algorithm designers.

## 1.18. Hard Processor System (HPS)

The Intel Stratix 10 SoC Hard Processor System (HPS) is Intel's industry leading third generation HPS. Leveraging the performance of Intel's 14-nm Tri-Gate technology, Intel Stratix 10 SoC devices more than double the performance of previous generation SoCs with an integrated quad-core 64-bit ARM Cortex-A53. The HPS also enables system-wide hardware virtualization capabilities by adding a system memory management unit. These architecture improvements ensure that Intel Stratix 10 SoCs will meet the requirements of current and future embedded markets, including wireless and wireline communications, data center acceleration, and numerous military applications.



## 1.19. Power Management

Intel Stratix 10 devices leverage the advanced Intel 14-nm Tri-Gate process technology, the all new HyperFlex core architecture to enable Hyper-Folding, power gating, and several optional power reduction techniques to reduce total power consumption by as much as 70% compared to previous generation high-performance Stratix V devices.

Intel Stratix 10 standard power devices (-V) are SmartVID devices. The core voltage supplies (VCC and VCCP) for each SmartVID device must be driven by a PMBus voltage regulator dedicated to that Intel Stratix 10 device. Use of a PMBus voltage regulator for each SmartVID (-V) device is mandatory; it is not an option. A code is programmed into each SmartVID device during manufacturing that allows the PMBus voltage regulator to operate at the optimum core voltage to meet the device performance specifications.

With the new HyperFlex core architecture, designs can run 2X faster than previous generation FPGAs. With 2X performance and same required throughput, architects can cut the data path width in half to save power. This optimization is called Hyper-Folding. Additionally, power gating reduces static power of unused resources in the FPGA by powering them down. The Intel Quartus Prime software automatically powers down specific unused resource blocks such as DSP and M20K blocks, at configuration time.

The optional power reduction techniques in Intel Stratix 10 devices include:

- **Available Low Static Power Devices**—Intel Stratix 10 devices are available with a fixed core voltage that provides lower static power than the SmartVID standard power devices, while maintaining device performance

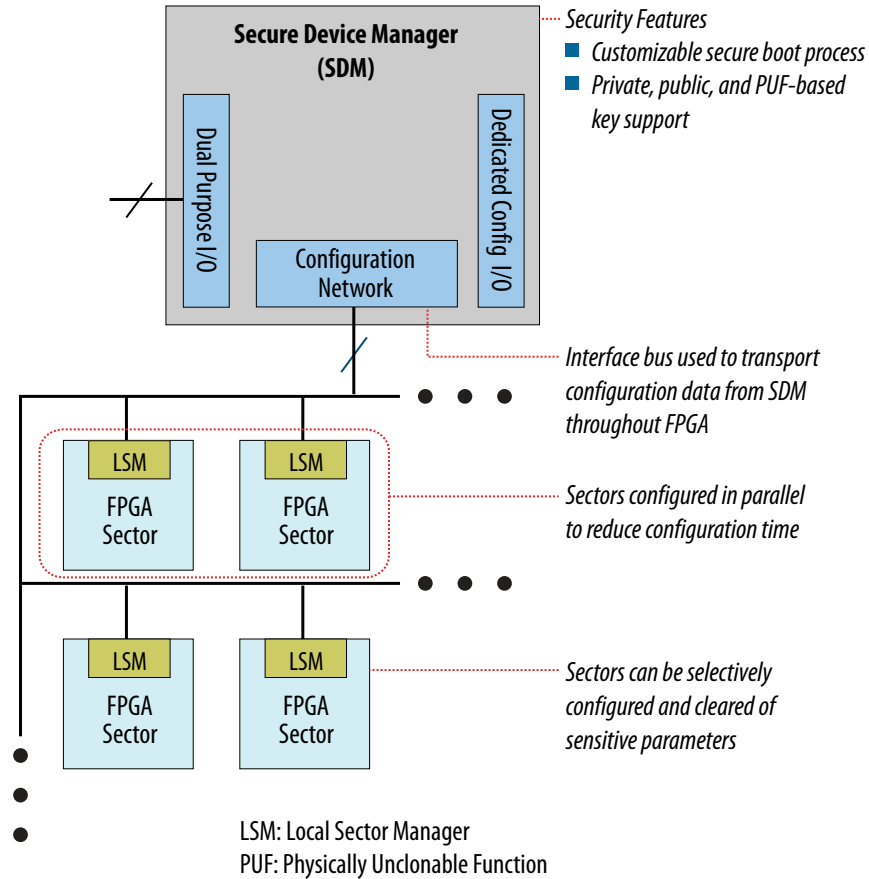
Furthermore, Intel Stratix 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 50% less power than the equivalent soft logic implementations.

## 1.20. Device Configuration and Secure Device Manager (SDM)

All Intel Stratix 10 devices contain a Secure Device Manager (SDM), which is a dedicated triple-redundant processor that serves as the point of entry into the device for all JTAG and configuration commands. The SDM also bootstraps the HPS in SoC devices ensuring that the HPS can boot using the same security features that the FPGA devices have.



Figure 14. SDM Block Diagram



During configuration, Intel Stratix 10 devices are divided into logical sectors, each of which is managed by a local sector manager (LSM). The SDM passes configuration data to each of the LSMs across the on-chip configuration network. This allows the sectors to be configured independently, one at a time, or in parallel. This approach achieves simplified sector configuration and reconfiguration, as well as reduced overall configuration time due to the inherent parallelism. The same sector-based approach is used to respond to single-event upsets and security attacks.

While the sectors provide a logical separation for device configuration and reconfiguration, they overlay the normal rows and columns of FPGA logic and routing. This means there is no impact to the Intel Quartus Prime software place and route, and no impact to the timing of logic signals that cross the sector boundaries.



The physical layout of the CRAM array is optimized to make the majority of multi-bit upsets appear as independent single-bit or double-bit errors which are automatically corrected by the integrated CRAM ECC circuitry. In addition to the CRAM protection, the user memories also include integrated ECC circuitry and are layout optimized for error detection and correction.

The SEU error detection and correction hardware is supported by both soft IP and the Intel Quartus Prime software to provide a complete SEU mitigation solution. The components of the complete solution include:

- Hard error detection and correction for CRAM and user M20K memory blocks
- Optimized physical layout of memory cells to minimize probability of SEU
- Sensitivity processing soft IP that reports if CRAM upset affects a used or unused bit
- Fault injection soft IP with the Intel Quartus Prime software support that changes state of CRAM bits for testing purposes
- Hierarchy tagging in the Intel Quartus Prime software
- Triple Mode Redundancy (TMR) used for the Secure Device Manager and critical on-chip state machines

In addition to the SEU mitigation features listed above, the Intel 14-nm Tri-Gate process technology used for Intel Stratix 10 devices is based on FinFET transistors which have reduced SEU susceptibility versus conventional planar transistors.

## 1.26. Document Revision History for the Intel Stratix 10 GX/SX Device Overview

Document Version	Changes
2018.08.08	Made the following changes: <ul style="list-style-type: none"><li>• Changed the specs for QDRII+ and QDRII+ Xtreme and added specs for QDRIV in the "External Memory Interface Performance" table.</li><li>• Updated description of the power options in the "Sample Ordering COde and Available Options for Intel Stratix 10 Devices" figure.</li><li>• Changed the description of the technology and power management features in the "Intel Stratix 10 FPGA and SoC Common Device Features" table.</li><li>• Changed the description of SmartVID in the "Power Management" section.</li><li>• Changed the direction arrow from the coefficient registers block in the "DSP Block: High Precision Fixed Point Mode" figure.</li></ul>
2017.10.30	Made the following changes: <ul style="list-style-type: none"><li>• Removed the embedded eSRAM feature globally.</li><li>• Removed the Low Power (VID) and Military operating temperature options, and package code 53 from the "Sample Ordering Code and Available Options for Stratix 10 Devices" figure.</li><li>• Changed the Maximum transceiver data rate (chip-to-chip) specification for L-Tile devices in the "Key Features of Intel Stratix 10 Devices Compared to Stratix V Devices" table.</li></ul>
2016.10.31	Made the following changes: <ul style="list-style-type: none"><li>• Changed the number of available transceivers to 96, globally.</li><li>• Changed the single-precision floating point performance to 10 TeraFLOPS, globally.</li><li>• Changed the maximum datarate to 28.3 Gbps, globally.</li><li>• Changed some of the features listed in the "Stratix 10 GX/SX Device Overview" section.</li><li>• Changed descriptions for the GX and SX devices in the "Stratix 10 Family Variants" section.</li><li>• Changed the "Sample Ordering Code and Available Options for Stratix 10 Devices" figure.</li></ul>
continued...	



Document Version	Changes
	<ul style="list-style-type: none"> <li>• Changed the features listed in the "Key Features of Stratix 10 Devices Compared to Stratix V Devices" table.</li> <li>• Changed the descriptions of the following areas of the "Stratix 10 FPGA and SoC Common Device Features" table: <ul style="list-style-type: none"> <li>— Transceiver hard IP</li> <li>— Internal memory blocks</li> <li>— Core clock networks</li> <li>— Packaging</li> </ul> </li> <li>• Reorganized and updated all tables in the "Stratix 10 FPGA and SoC Family Plan" section.</li> <li>• Removed the "Migration Between Arria 10 FPGAs and Stratix 10 FPGAs" section.</li> <li>• Removed footnotes from the "Transceiver PCS Features" table.</li> <li>• Changed the HMC description in the "External Memory and General Purpose I/O" section.</li> <li>• Changed the number of fPLLs in the "Fractional Synthesis PLLs and I/O PLLs" section.</li> <li>• Clarified HMC data width support in the "Key Features of the Stratix 10 HPS" table.</li> <li>• Changed the description in the "Internal Embedded Memory" section.</li> <li>• Changed the datarate for the Standard PCS and SDI PCS features in the "Transceiver PCS Features" table.</li> <li>• Added a note to the "PCI Express Gen1/Gen2/Gen3 Hard IP" section.</li> <li>• Updated the "Key Features of the Stratix 10 HPS" table.</li> <li>• Changed the description for the Cache coherency unit in the "Key Features of the Stratix 10 HPS" table.</li> <li>• Changed the description for the external SDRAM and Flash memory interfaces for HPS in the "Key Features of the Stratix 10 HPS" table.</li> </ul>
2015.12.04	Initial release.